

Electro-Science Laboratories, Inc.

416 East Church Road • King of Prussia, PA 19406-2625, U.S.A 610-272-8000 • Fax: 610-272-6759 • www.ElectroScience.com • Sales@ElectroScience.com

CERMET GOLD CONDUCTOR

8881-B

ESL 8881-B is a newly developed thin printing MICRO-LOK® gold paste designed for use on 96% alumina substrates, or with 4905-C dielectric. The fired film exhibits strong adhesion to both bare alumina and 4905-C dielectric and is easily etchable. ESL 8881-B exhibits high coverage and excellent wire bondability. Although the fired thickness is in the range of 6-8 micrometers, the film is very dense, exhibits no centerline depression and has good line resolution.

HIGHLIGHTS OF 8881-B ARE:

Thin, very dense fired film
Excellent printability
Fine line resolution
Excellent etchability
Low resistivity
Excellent thermosonic gold wire bonding and thermal aging 850°C firing temperature

PASTE DATA

RHEOLOGY: Thixotropic, screen printable paste

VISCOSITY:

(Brookfield HBT, SC4-14 spindle, 10 rpm, 25.5°C±0.5°C) 250±25 Pa·s

BONDING MECHANISM: MICRO-LOK®

SHELF LIFE: (at 20°C) 6 months

PROCESSING

SCREEN MESH / EMULSION: 325/25 μm

LEVELING TIME: (at 20°C) 5-10 minutes

DRYING AT 125°C: 10-15 minutes

8881-B 9710-C

ESL Affiliates

Japan: ESL-Nippon Company, Ltd. • Sukegawa Bldg. • 6th floor • 3-4 Yanagibashi 1-chome • Taito-ku • Tokyo 111, Japan • Tel: (011-81)-3-3864-8521 • Fax: (011-81)-3-3864-9270 NipponSales@ESLNippon.com

FIRING TEMPERATURE:

OPTIMUM: 850°C

TIME AT PEAK: 10 minutes

RATE OF ASCENT / DESCENT: 60°C-100°C/minutes

SUBSTRATE FOR CALIBRATION: 96% alumina

THINNER: ESL 413

TYPICAL PROPERTIES

FIRED THICKNESS: 6-8 μm

RESISTIVITY: (at 8 μ m fired) ~ 3.5 m Ω /square

(at 7 μ m fired) ~ 4.0 m Ω /square

PRINTING RESOLUTION:

(Line/Space) (325 mesh stainless steel) 75 μm x 75 μm

(Special Screen) 50 μ m x 50 μ m

THERMOSONIC GOLD WIREBONDING:

(25 µm gold wire) Initial After 48 hours at 150°C

(On bare 96% alumina)14 grams10 grams(On 4905-C dielectric)14 grams10 grams

SOLDERED ADHESION:

(2 mm x 2 mm pads, 80 Au/20 Sn solder, on 96% alumina) 64 N